



1. MATERIALS AND FINISH
  - 1.1 HOUSING MATERIALS:  
THERMOPLASTIC.
  - 1.2 CONTACTS:  
COPPER ALLOY.
  - 1.3 PLATING:  
CONTACT AREA PLATING GOLD  
TIN/LEAD PLATING ON SOLDER TAILS  
UNDER PLATING NICKEL .
2. SPECIFICATIONS
  - 2.1 CURRENT RATING:  
1 A MAX.
  - 2.2 INSULATION RESISTANCE:  
1000M $\Omega$ /M.
  - 2.3 DIELECTRIC WITHSTANDING VOLTAGE:  
500V (r.m.s) AC FOR 1 MINUTE.
  - 2.4 CONTACT RESISTANCE:  
m30MAX.
  - 2.5 OPERATING TEMPERATURE:  
°C ?-485.



PART NO. 8173-3681		CHECKED BY CY		TOLERANCES ARE .X ± 0.3 .XX ± .XXX ± AWG	DESCRIP TION: SCSI II DIP 68PIN (4R) LEFT FEET			
FILE NO.		DRAWING BY			AREA	REVISIONS	HK	DATE
UNIT / mm	SCALE 1:1	PROJECTION						